

### **Amendments to the Specification**

Please replace the paragraph beginning at page 14, line 5 with the following written paragraph:

--In other examples, radio frequency and/or thermal lamination processes are employed. Ultrasonic welding, radio frequency welding, and thermal lamination are all types of thermoplastic reflow processes which are suitable processes for securing substrate 52 to fabric 48. An adhesive may also be used between flexible substrate 52 and fabric 48 and/or sewing techniques may be used to secure flexible substrate 52 to fabric 48. In one preferred embodiment, an additional layer of material 282 (Fig. 20) may be used to reinforce the stitch area 284. Also, substrate 52 may be secured to fabric 48 using rivets 270 (Fig. 19A), plated through holes 272 (Fig. 19B), VELCRO<sup>®</sup> patches 274 (Fig. 19C), or zippers 278 (Fig. 19D). Patches 274 (Fig. 19C) may be of any size and shape based on the particular application. Alternatively, the complete area of the flex circuit is laminated or otherwise secured to the textile article. In the typical example, electronic components 50, Fig. 4 are then populated on flex circuit 42 after it is secured to fabric 48. In other examples, select or even all of the electronic components populate flex circuit 42 before it is secured to fabric 48.--